PCN Number:	20170504000A	PCN Date:	July 26, 2017
Title:	Qualification of TI Chengdu BUMP (CBUMP) as an Additional Bump and TI Chengdu A/T (CDAT) as an Assembly site for the BQ25898 Device		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Oct 26, 2017	Estimated Sample Availability:	Provided upon Request

Change Type:

☒	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☒	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☒	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

Revision A is to announce the addition of new devices that were not included on the original PCN notification. These new devices are highlighted and **bolded** in the device list below. The expected first shipment date for these new devices will be 90 days from this notice for these newly added devices only.

Texas Instruments is pleased to announce the qualification of TI Chengdu BUMP (CBUMP) as an Additional Bump and TI Chengdu A/T (CDAT) as an additional Assembly site for the BQ25898CYFFR/T. There is no construction differences in devices built between the various sites.

Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Anticipated impact on Material Declaration

☒	No Impact to the Material Declaration	☐	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website.

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly City
TI Clark	QAB	PHL	Angeles City, Pampanga
CDAT	**CDA**	**CHN**	**Chengdu**

Sample product shipping label (not actual product label)

Topside Device marking (if included):
Assembly site code for QAB= I
Assembly site code for CDA = 8

Product Affected			
BQ25898CYFFR	BQ25898CYFFT	**BQ25898YFFR**	**BQ25898YFFT**

Qualification Report

Chengdu BUMP (CBUMP) start-up for BOPCOA - PHASE 1B (BQ25898CYFFR)

Approve Date 13-Jul-2017

Product Attributes

Attributes	Qual Device: BQ25898CYFFR
Assembly Site	CHENGDU A/T
Package Family	WCSP
Flammability Rating	UL 94 V-0
Wafer Fab Supplier	RFAB
Wafer Fab Process	LBC7

- QBS: Qual By Similarity
- Qual Device BQ25898CYFFR is qualified at LEVEL1-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: BQ25898CYFFR
BLR	BLR High Acceleration Shock 10kG	18 Cycles	3/99/0
BLR	BLR Random Vibration 5G 5-500Hz	30 Minutes	3/99/0
BLR	BLR Temp Cycle -40/85c	1000 Cycles	3/99/0
BLR	BLR Unbiased Temperature and Humidity, 85C/85%RH	1000 Hours	3/99/0
ED	Electrical Characterization, side by side	Per Datasheet Parameters	Pass
HBM	ESD - HBM	2000 V	3/9/0
HTSL	High Temp Storage Bake 170C	420 Hours	3/231/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass

Type	Test Name / Condition	Duration	Qual Device: BQ25898CYFFR
MQ	Manufacturability (Bump)	(per mfg. Site specification)	Pass
PD	Physical Dimensions	(per mechanical drawing)	3/15/0
SBS	Bump-shear	unstressed	5/150/0
TC	Temperature Cycle, -55/125C	700 Cycles	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	3/231/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com